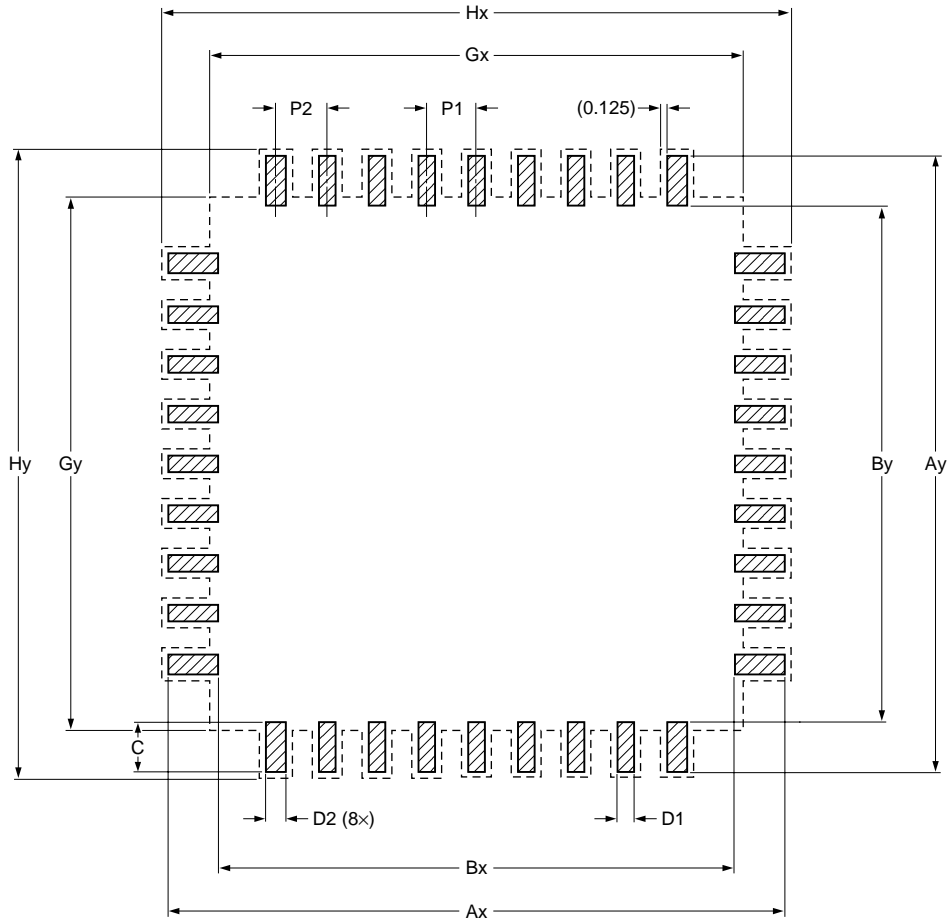


Footprint information for reflow soldering of LQFP44 package

SOT389-1



Generic footprint pattern  
Refer to the package outline drawing for actual layout

- solder land
- occupied area

DIMENSIONS in mm

| P1    | P2    | Ax     | Ay     | Bx     | By     | C     | D1    | D2    | Gx     | Gy     | Hx     | Hy     |
|-------|-------|--------|--------|--------|--------|-------|-------|-------|--------|--------|--------|--------|
| 0.800 | 0.850 | 13.300 | 13.300 | 10.300 | 10.300 | 1.500 | 0.500 | 0.600 | 10.500 | 10.500 | 13.550 | 13.550 |